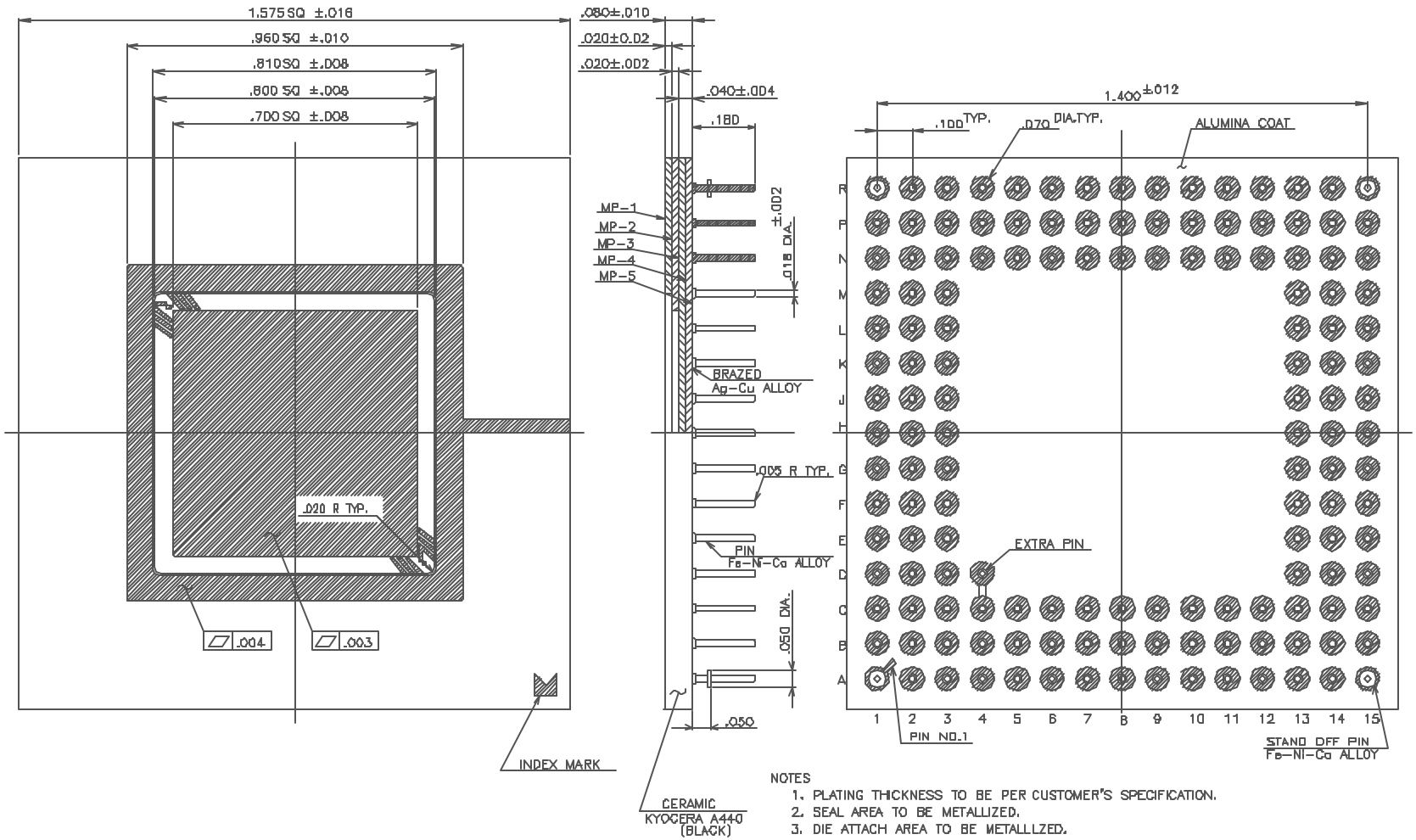
CPGA145T15x15-N



NOTES

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. SEAL AREA TO BE METALLIZED.
3. DIE ATTACH AREA TO BE METALLIZED.
4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
5. LEAD RESISTANCE:B/F NO,18,19,54,55,90,91,126,127--------230mOHMS MAX.
   B/F NO.1,37,73,109,9,30,45,60,81,102,117,138----250mOHMS MAX.
   THE OTHERS ----------800mOHMS MAX.
6. OPEN SHORT TEST TO BE PERFORMED ON ALL PINS.

MODIFICATION					
B	REDREWN	MR.20.01	N.I	A.F/T.A	M.K
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME: 145 PIN GRID ARRAY PACKAGE

SCALE: 5/1

MATERIAL: AS INDICATED

TOLERANCE: ±.005

KYOCERA CORPORATION
KYOTO JAPAN

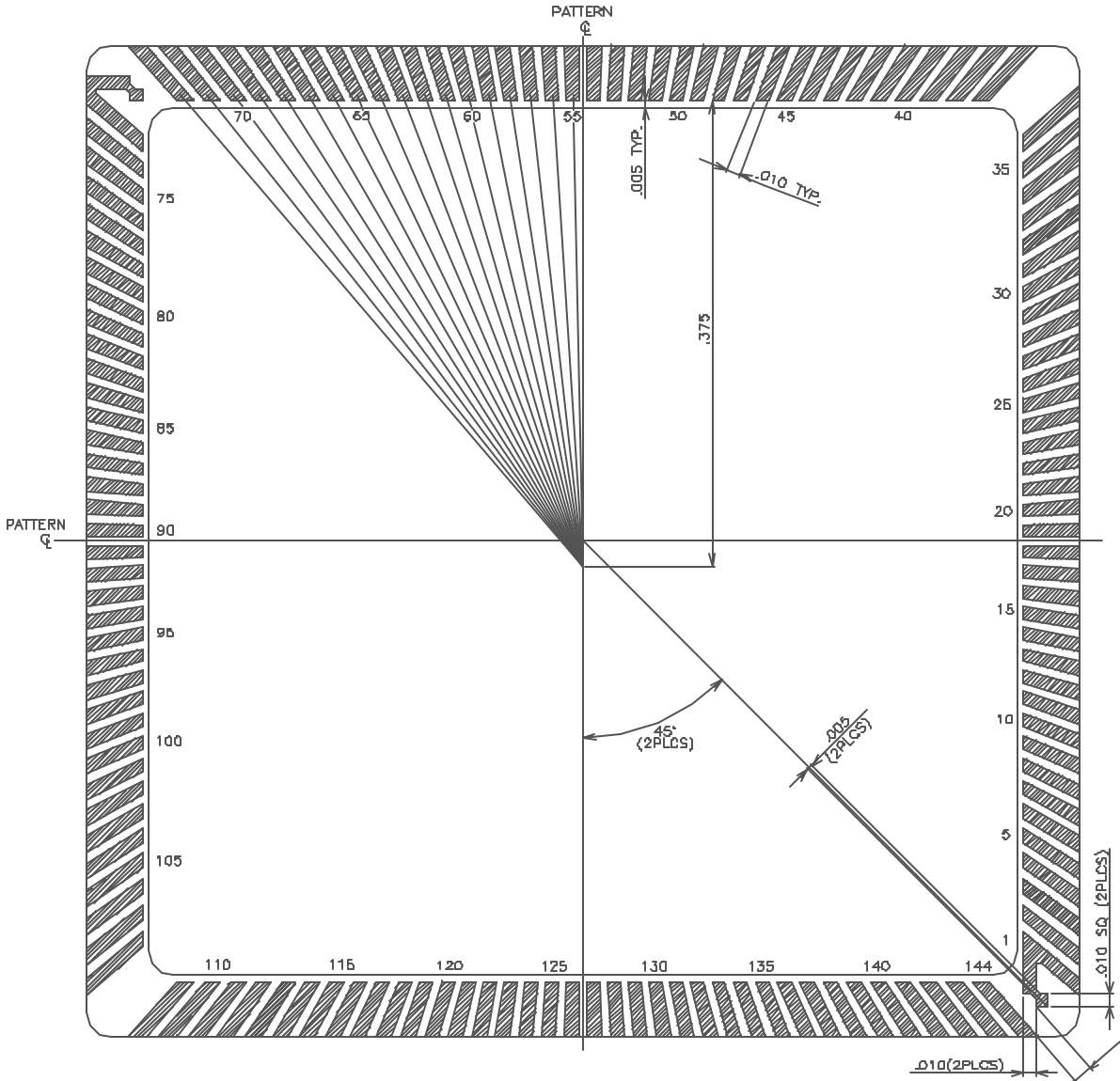
PB145S499-1 S=Q D=D

DRAWN	CHECKED	APPROVED	DATE
N.I	A.F/T.A	M.K	MR.20.01

DRAWING NO. KD-PB6499-B

SHEET 1/3

CPG14434



W/B NO.	W/B ANGLE
55	1.260°
56	3.779°
57	6.293°
58	8.797°
59	11.287°
60	13.757°
61	16.205°
62	18.624°
63	21.012°
64	23.364°
65	25.677°
66	27.948°
67	30.174°
68	32.352°
69	34.481°
70	36.556°
71	38.582°
72	40.552°

NOTES,

7. THIS TABLE SHOWS 1/8 OF THE TOTAL AND IS SYMMETRICAL TO THE CENTER LINE.
8. WIRE BOND FINGERS TO BE MIN .004 INCH FLAT ACROSS THE WIDTH FOR THE FULL LENGTH OF THE BOND FINGERS (CRITICAL AREA).
9. DIE ATTACH AREA TO BE FLAT WITHIN .003 INCH.
10. PRODUCT TO MEET THE ENVIRONMETAL AND MECHANICAL REQUIREMENT OF MIL-STD 883C.

BONDING PATTERN

MODIFICATION										
						NAME 145 PIN GRID ARRAY PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE
						SCALE 16/1	MATERIAL	N.I	AF/TA	M.K	MAR.20.'91
A	REDRAWN	MAR.20.'91	N.I	AF/TA	M.K	KYOCERA	KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P86499-B			SHEET 2/3
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						

WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	D3	27	M1	53	R8	79	L14	105	D13	131	B6
2	C2	28	N1	54	N8	80	M15	106	C13	132	C6
3	B1	29	M2	55	N9	81	K13	107	B14	133	A5
4	D2	30	L3	56	R9	82	K14	108	A15	134	B5
5	E3	31	N2	57	R10	83	L15	109	C12	135	A4
6	C1	32	P1	58	P9	84	J14	110	B13	136	A3
7	E2	33	M3	59	P10	85	J13	111	A14	137	B4
8	D1	34	N3	60	N10	86	K15	112	B12	138	C5
9	F3	35	P2	61	R11	87	J15	113	C11	139	B3
10	F2	36	R1	62	P11	88	H14	114	A13	140	A2
11	E1	37	N4	63	R12	89	H15	115	B11	141	C4
12	G2	38	P3	64	R13	90	H13	116	A12	142	C3
13	G3	39	R2	65	P12	91	G13	117	C10	143	B2
14	F1	40	P4	66	N11	92	G15	118	B10	144	A1
15	G1	41	N5	67	P13	93	F15	119	A11		
16	H2	42	R3	68	R14	94	G14	120	B9		
17	H1	43	P5	69	N12	95	F14	121	C9		
18	H3	44	R4	70	N13	96	F13	122	A10		
19	J3	45	N6	71	P14	97	E15	123	A9		
20	J1	46	P6	72	R15	98	E14	124	B8		
21	K1	47	R5	73	M13	99	D15	125	A8		
22	J2	48	P7	74	N14	100	C15	126	C8		
23	K2	49	N7	75	P15	101	D14	127	C7		
24	K3	50	R6	76	M14	102	E13	128	A7		
25	L1	51	R7	77	L13	103	C14	129	A6		
26	L2	52	P8	78	N15	104	B15	130	B7		

NOTES,

11. D4 IS EXTRA PIN USED FOR ORIENTATION AND IS CONNECTED TO C4(141).
12. ALL LEADS TO MEET THE LEAD INTEGRITY CRITERIA OF MIL-STD 883C METHOD 2004-A

MODIFICATION					
B	REDRAWN	MAR.20.'01	N.I	A.F/T.A	K.M
	CHANGED	DATE	DRAWN	CHECKED	APPROVED

NAME: 145 PIN GRID ARRAY PACKAGE

SCALE: ×

MATERIAL: —

TOLERANCE: UNLESS OTHERWISE SPECIFIED — THIRD ANGLE PROJECTION

KYOCERA CORPORATION KYOTO JAPAN

DRAWN	CHECKED	APPROVED	DATE
N.I	A.F/T.A	M.K	MAR.20.'01

DRAWING NO. KD-PB6499-B

SHEET 3/3